

# MBR860MFS, NRVB860MFS

## SWITCHMODE Power Rectifiers

These state-of-the-art devices have the following features:

### Features

- Low Power Loss / High Efficiency
- New Package Provides Capability of Inspection and Probe After Board Mounting
- Guardring for Stress Protection
- Low Forward Voltage Drop
- 175°C Operating Junction Temperature
- Wettable Flacks Option Available
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable

- These are Pb-Free Devices

### Mechanical Characteristics:

- Case: Epoxy, Molded
- Epoxy Meets Flammability Rating UL 94-0 @ 0.125 in.
- Lead Finish: 100% Matte Sn (Tin)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL 1 Requirements

### MAXIMUM RATINGS

| Rating                                                                                                            | Symbol                          | Value       | Unit |
|-------------------------------------------------------------------------------------------------------------------|---------------------------------|-------------|------|
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage                            | $V_{RRM}$<br>$V_{RWM}$<br>$V_R$ | 60          | V    |
| Average Rectified Forward Current<br>(Rated $V_R$ , $T_C = 165^\circ\text{C}$ )                                   | $I_{F(AV)}$                     | 8.0         | A    |
| Peak Repetitive Forward Current,<br>(Rated $V_R$ , Square Wave,<br>20 kHz, $T_C = 165^\circ\text{C}$ )            | $I_{FRM}$                       | 16          | A    |
| Non-Repetitive Peak Surge Current<br>(Surge Applied at Rated Load<br>Conditions Halfwave, Single<br>Phase, 60 Hz) | $I_{FSM}$                       | 150         | A    |
| Storage Temperature Range                                                                                         | $T_{stg}$                       | -65 to +175 | °C   |
| Operating Junction Temperature                                                                                    | $T_J$                           | -55 to +175 | °C   |
| Unclamped Inductive Switching<br>Energy (10 mH Inductor,<br>Non-repetitive)                                       | $E_{AS}$                        | 40          | mJ   |
| ESD Rating (Human Body Model)                                                                                     |                                 | 3B          |      |
| ESD Rating (Machine Model)                                                                                        |                                 | M4          |      |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

NOTE: The heat generated must be less than the thermal conductivity from Junction-to-Ambient:  $dPD/dT_J < 1/RJA$ .

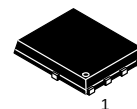


**ON Semiconductor®**

<http://onsemi.com>

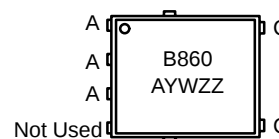
## SCHOTTKY BARRIER RECTIFIERS 8 AMPERES 60 VOLTS

1,2,3  5,6



SO-8 FLAT LEAD  
CASE 488AA  
STYLE 2

### MARKING DIAGRAM



B860 = Specific Device Code  
A = Assembly Location  
Y = Year  
W = Work Week  
ZZ = Lot Traceability

### ORDERING INFORMATION

| Device        | Package              | Shipping†             |
|---------------|----------------------|-----------------------|
| MBR860MFST1G  | SO-8 FL<br>(Pb-Free) | 1500 /<br>Tape & Reel |
| MBR860MFST3G  | SO-8 FL<br>(Pb-Free) | 5000 /<br>Tape & Reel |
| NRVB860MFST1G | SO-8 FL<br>(Pb-Free) | 1500 /<br>Tape & Reel |
| NRVB860MFST3G | SO-8 FL<br>(Pb-Free) | 5000 /<br>Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# MBR860MFS, NRVB860MFS

## THERMAL CHARACTERISTICS

| Characteristic                                                                                                            | Symbol          | Typ | Max | Unit |
|---------------------------------------------------------------------------------------------------------------------------|-----------------|-----|-----|------|
| Thermal Resistance, Junction-to-Case, Steady State<br>(Assumes 600 mm <sup>2</sup> 1 oz. copper bond pad, on a FR4 board) | $R_{\theta JC}$ | –   | 2.0 | °C/W |

## ELECTRICAL CHARACTERISTICS

|                                                                                                                                           |       |              |              |    |
|-------------------------------------------------------------------------------------------------------------------------------------------|-------|--------------|--------------|----|
| Instantaneous Forward Voltage (Note 1)<br>( $i_F = 8$ Amps, $T_J = 125^\circ\text{C}$ )<br>( $i_F = 8$ Amps, $T_J = 25^\circ\text{C}$ )   | $V_F$ | 0.60<br>0.65 | 0.72<br>0.80 | V  |
| Instantaneous Reverse Current (Note 1)<br>(Rated dc Voltage, $T_J = 125^\circ\text{C}$ )<br>(Rated dc Voltage, $T_J = 25^\circ\text{C}$ ) | $i_R$ | 25<br>0.015  | 75<br>0.150  | mA |

1. Pulse Test: Pulse Width = 300  $\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

## TYPICAL CHARACTERISTICS

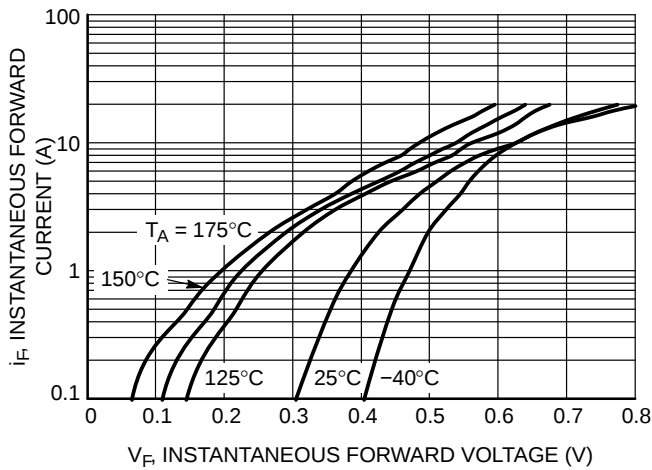


Figure 1. Typical Instantaneous Forward Characteristics

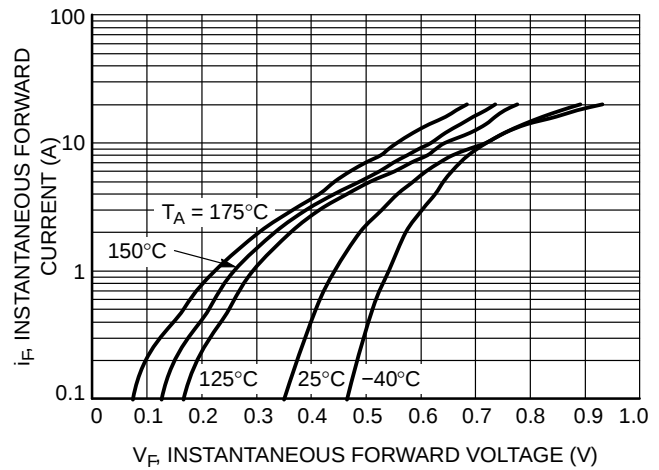


Figure 2. Maximum Instantaneous Forward Characteristics

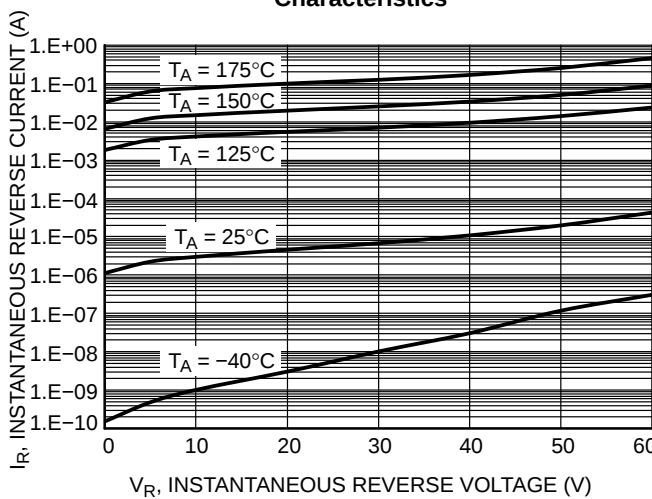


Figure 3. Typical Reverse Characteristics

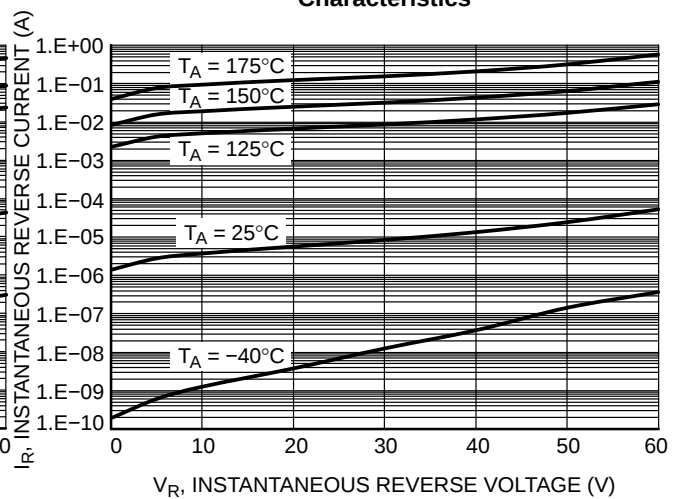


Figure 4. Maximum Reverse Characteristics

# MBR860MFS, NRVB860MFS

## TYPICAL CHARACTERISTICS

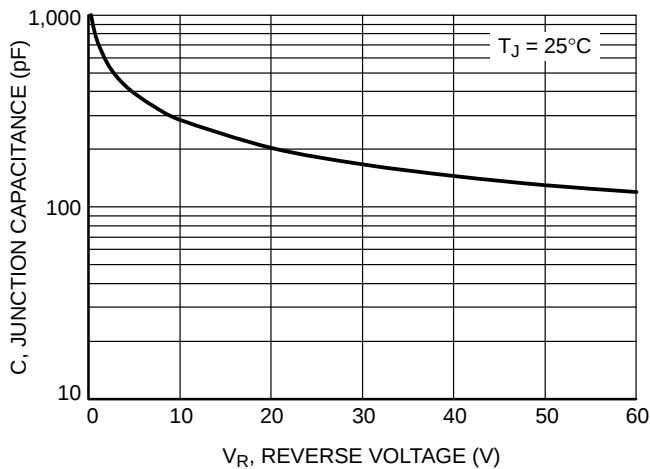


Figure 5. Typical Junction Capacitance

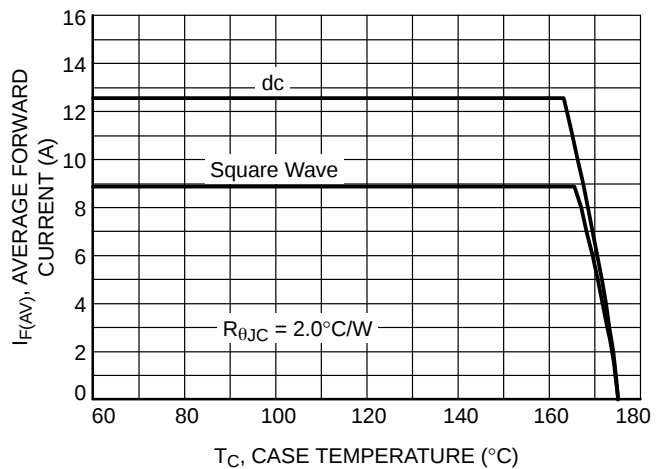


Figure 6. Current Derating TO-220AB

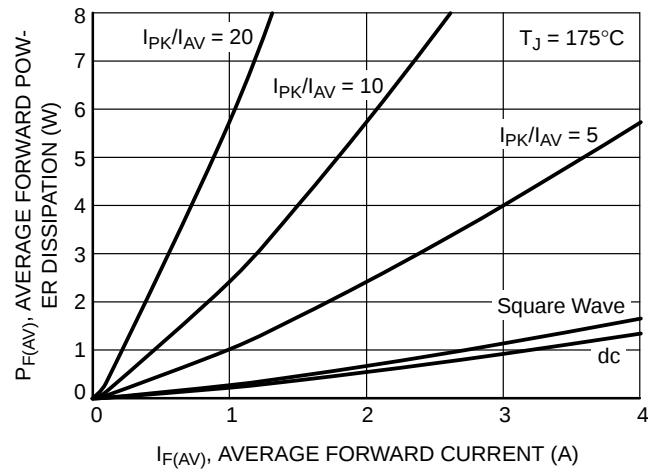


Figure 7. Forward Power Dissipation

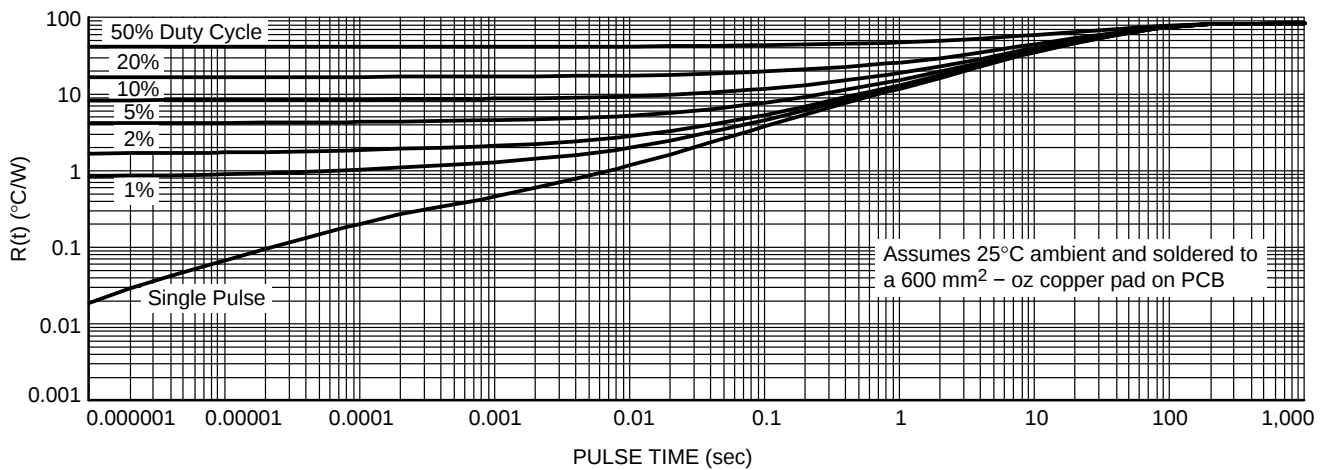


Figure 8. Thermal Response

# MBR860MFS, NRVB860MFS

## PACKAGE DIMENSIONS

DFN6 5x6, 1.27P  
(SO-8FL)  
CASE 488AA  
ISSUE H

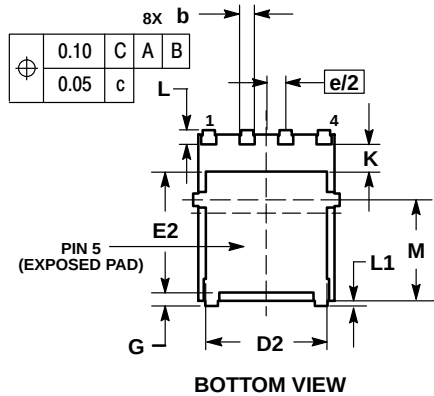
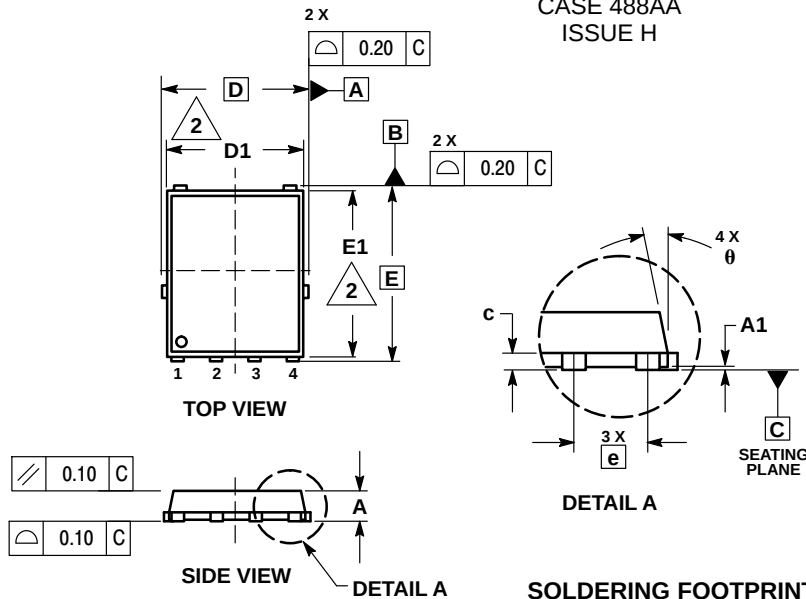
### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

| DIM | MILLIMETERS |      |      |
|-----|-------------|------|------|
|     | MIN         | NOM  | MAX  |
| A   | 0.90        | 1.00 | 1.10 |
| A1  | 0.00        | ---  | 0.05 |
| b   | 0.33        | 0.41 | 0.51 |
| c   | 0.23        | 0.28 | 0.33 |
| D   | 5.15 BSC    |      |      |
| D1  | 4.70        | 4.90 | 5.10 |
| D2  | 3.80        | 4.00 | 4.20 |
| E   | 6.15 BSC    |      |      |
| E1  | 5.70        | 5.90 | 6.10 |
| E2  | 3.45        | 3.65 | 3.85 |
| e   | 1.27 BSC    |      |      |
| G   | 0.51        | 0.61 | 0.71 |
| K   | 1.20        | 1.35 | 1.50 |
| L   | 0.51        | 0.61 | 0.71 |
| L1  | 0.05        | 0.17 | 0.20 |
| M   | 3.00        | 3.40 | 3.80 |
| θ   | 0°          | ---  | 12°  |

### STYLE 2:

- PIN 1. ANODE
- ANODE
- ANODE
- NO CONNECT
- CATHODE



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed at [www.onsemi.com/site/pdf/Patent-Marketing.pdf](http://www.onsemi.com/site/pdf/Patent-Marketing.pdf). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

## PUBLICATION ORDERING INFORMATION

### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor  
P.O. Box 5163, Denver, Colorado 80217 USA  
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada  
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada  
Email: [orderlit@onsemi.com](mailto:orderlit@onsemi.com)

N. American Technical Support: 800-282-9855 Toll Free  
USA/Canada  
Europe, Middle East and Africa Technical Support:  
Phone: 421 33 790 2910  
Japan Customer Focus Center  
Phone: 81-3-5817-1050

ON Semiconductor Website: [www.onsemi.com](http://www.onsemi.com)

Order Literature: <http://www.onsemi.com/orderlit>

For additional information, please contact your local Sales Representative

MBR860MFS/D

## Данный компонент на территории Российской Федерации

**Вы можете приобрести в компании MosChip.**

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

### Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: [info@moschip.ru](mailto:info@moschip.ru)

Skype отдела продаж:

moschip.ru

moschip.ru\_4

moschip.ru\_6

moschip.ru\_9